

SOT840-1

plastic thermal enhanced low profile land grid array package;
52 lands; resin based; body 8 x 7 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLLGA52R
Package type industry code	HLLGA52R
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		7.9	-	8	8.1	mm
E	package width		6.9	-	7	7.1	mm
A	seated height		[tbd]	-	1.4	1.4	mm
A ₂	package height		[tbd]	-	1.4	[tbd]	mm
n ₂	actual quantity of termination		-	-	52	-	



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x 1.4 mm

2. Package outline

HLLGA52R: plastic thermal enhanced low profile land grid array package;
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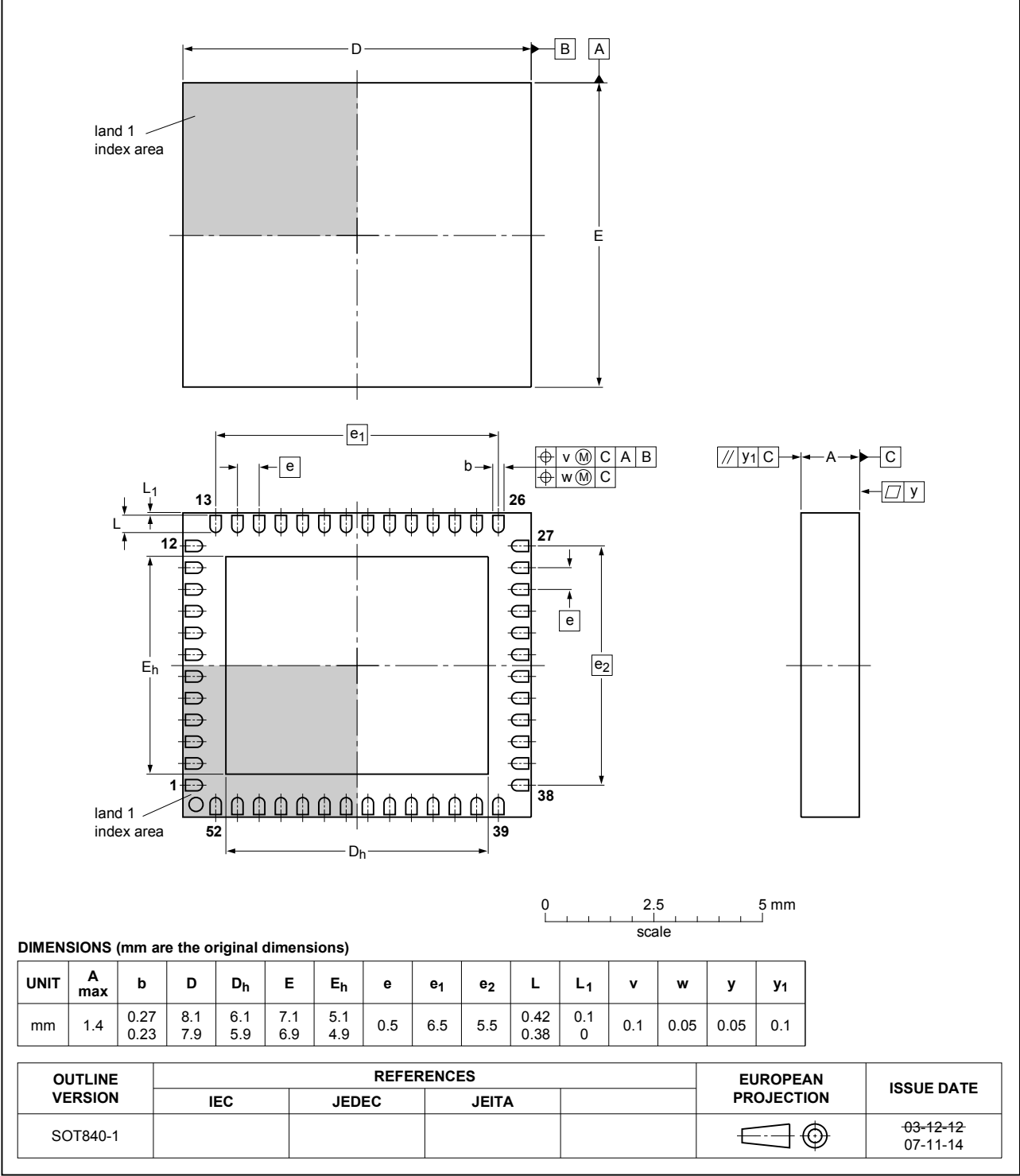


Fig. 1. Package outline HLLGA52R (SOT840-1)

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3. Legal information

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